These assemblies are ESD sensitive. ESD precautions shall be observed.
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

Components marked 'DNP' should not be populated.

Assembly Variant:

<table>
<thead>
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<th>PCB VIEWED FROM TOP SIDE</th>
<th>BOARD #: TIDA-01054</th>
<th>REV: E1</th>
<th>SUN REV: Not In VersionControl</th>
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<td></td>
<td>TID #: E1054</td>
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</table>

Plot Name = Top Assembly Drawing
Generated: 8/9/2017 2:24:11 PM

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